



Smart Systems (SmaSys2019&2020)

Guest Editors:

Prof. Dr. Hidemitsu Furukawa

Prof. Dr. Bungo Ochiai

Dr. Masato Makino

Dr. Ajit Khosla

Deadline for manuscript
submissions:

closed (31 July 2021)

Message from the Guest Editors

Dear Colleagues,

We are planning to publish a Special Issue on "Smart Systems" related to the International Conference of Smart Systems Engineering (SmaSys2019&2020). The Special Issue on "Smart Systems" provides opportunities for collaboration across a wide range of fields and technologies related to emerging smart systems. Smart systems regard broad scientific and engineering fields. They include organic materials, organic electronics, organic devices, biomaterials, biomedical and biosystem engineering, electrical engineering and informatics, mechanical systems engineering, smart flexible structure and systems, green materials and their processing, tourism engineering with agriculture and foods, and new engineering education.

All the participants of SmaSys2019&2020 and their colleagues, especially their students, are encouraged to submit their works to this Special Issue.

Prof. Dr. Hidemitsu Furukawa

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Dr. Ajit Khosla

Guest Editors





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Message from the Editor-in-Chief

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